

*Initials*

USPTO  
APR 20 2001

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Priority Application Serial No. .... 09/148,723  
Priority Filing Date ..... September 3, 1998  
Inventor ..... Warren M. Farnsworth et al.  
Assignee ..... Micron Technology, Inc.  
Priority Group Art Unit ..... 3729  
Priority Examiner ..... D. Tugbang  
Attorney's Docket No. ..... MI22-981  
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate

*#20/Sypl*

**RESPONSE TO FEBRUARY 27, 2001 OFFICE ACTION**  
**PRELIMINARY AMENDMENT TO ACCOMPANY REQUEST FOR**  
**CONTINUED EXAMINATION (RCE) TRANSMITTAL FILING**

To: BOX RCE  
Assistant Commissioner for Patents  
Washington, D.C. 20231

From: Frederick M. Fliegel, Ph.D.  
Tel. 509-624-4276; Fax 509-838-3424  
Wells, St. John, Roberts, Gregory & Matkin P.S.  
601 W. First Avenue, Suite 1300  
Spokane, WA 99201-3817

Sir:

Responsive to the Final Office Action dated February 27, 2001,

Applicant amends and remarks as follows:

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**AMENDMENTS**

*(Cancel claims 12, 16, 2nd claim 48-50)  
Add claims 48-50  
A.D. Tugbang)*

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